

REPAIRING ANOMALOUS STIFF PILLAR BUMPS

ABSTRACT OF THE DISCLOSURE

Generally, the subject matter disclosed herein relates to repairing anomalous stiff pillar bumps that may be detected above a metallization system of a semiconductor chip or wafer. One illustrative method disclosed herein includes, among other things, forming a pillar bump (703, 903) above a metallization system of a semiconductor chip, and forming a plurality of notches (725a, 725b, , 924) in the pillar bump (703, 903), wherein the plurality of notches are adapted to adjust a flexibility of the pillar bump (703, 903) when the pillar bump is exposed to a lateral force.

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Fig. 7a